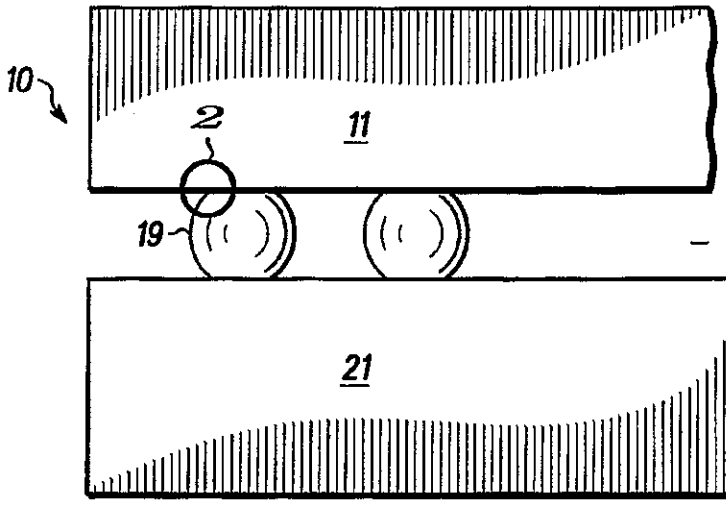


FIG. 1
- PRIOR ART -

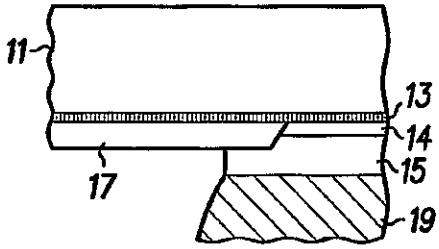


FIG. 2
- PRIOR ART -

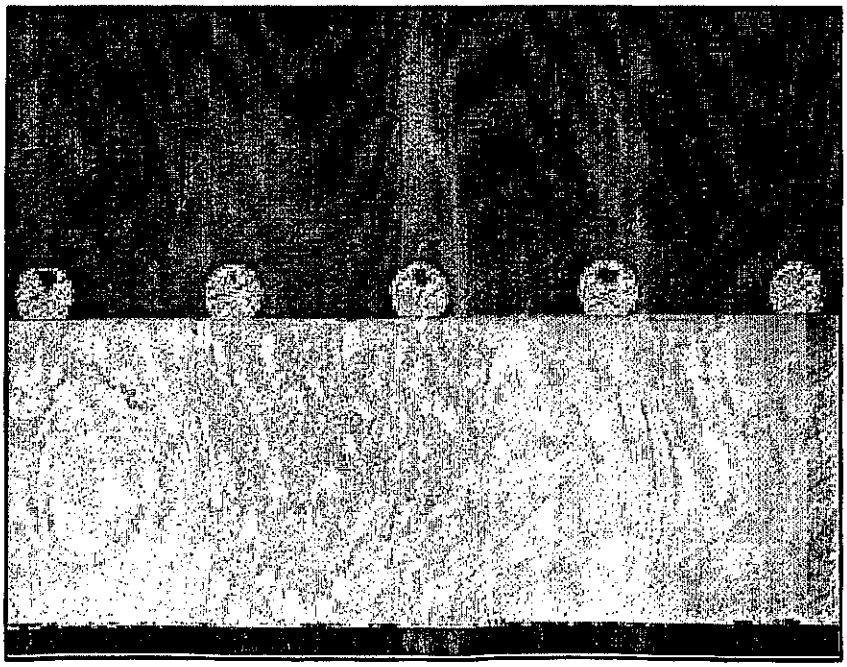


FIG. 3 - PRIOR ART -

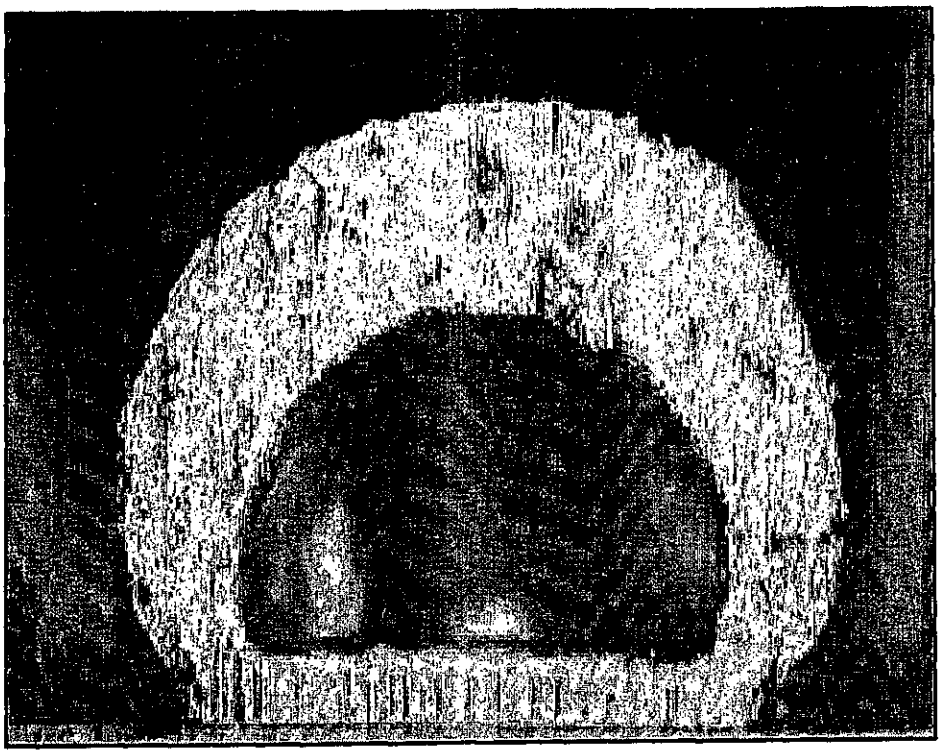


FIG. 4 - PRIOR ART -

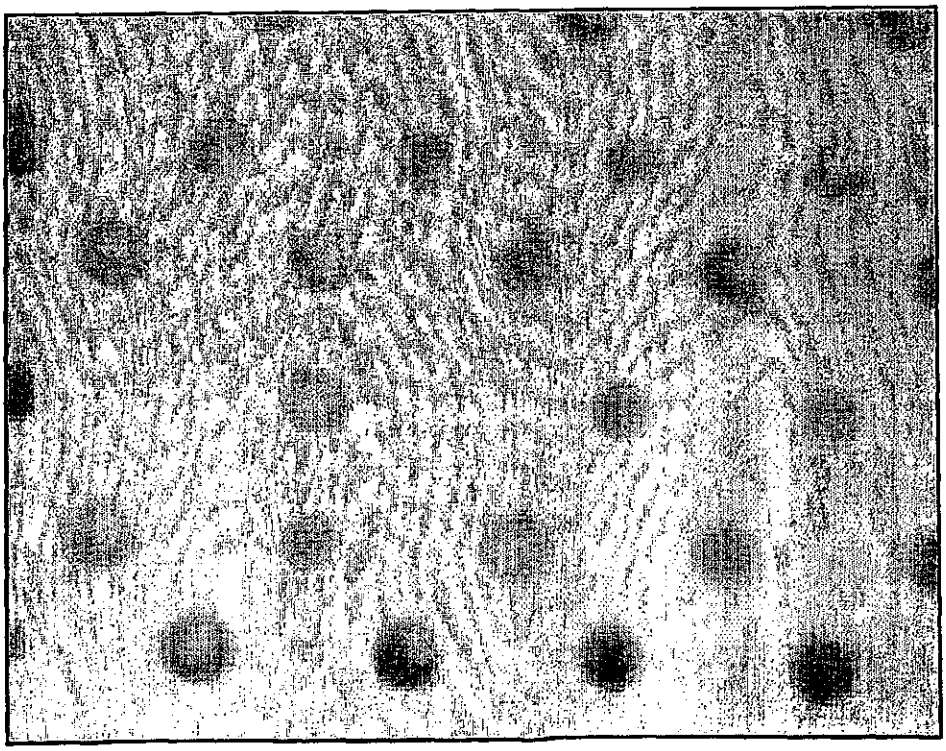


FIG. 5 - PRIOR ART -

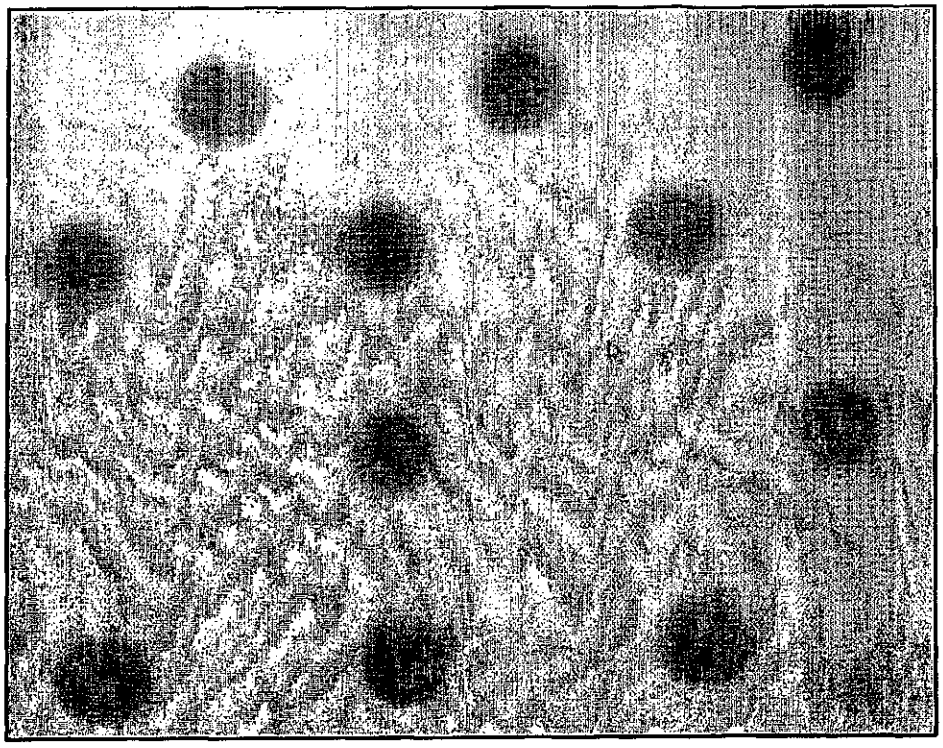


FIG. 6

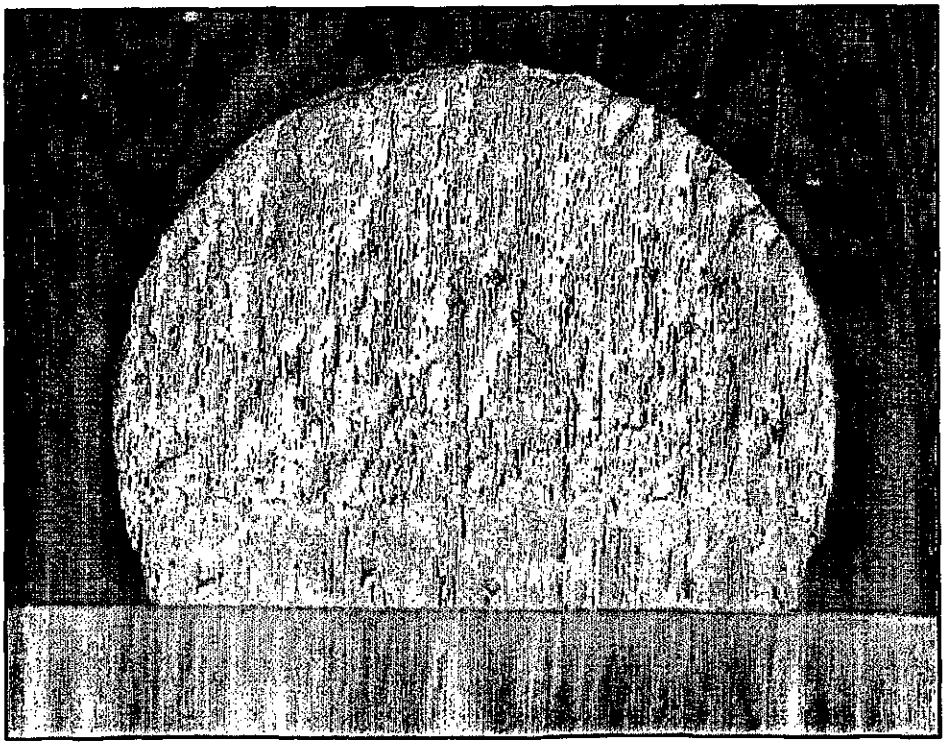


FIG. 7 - PRIOR ART -

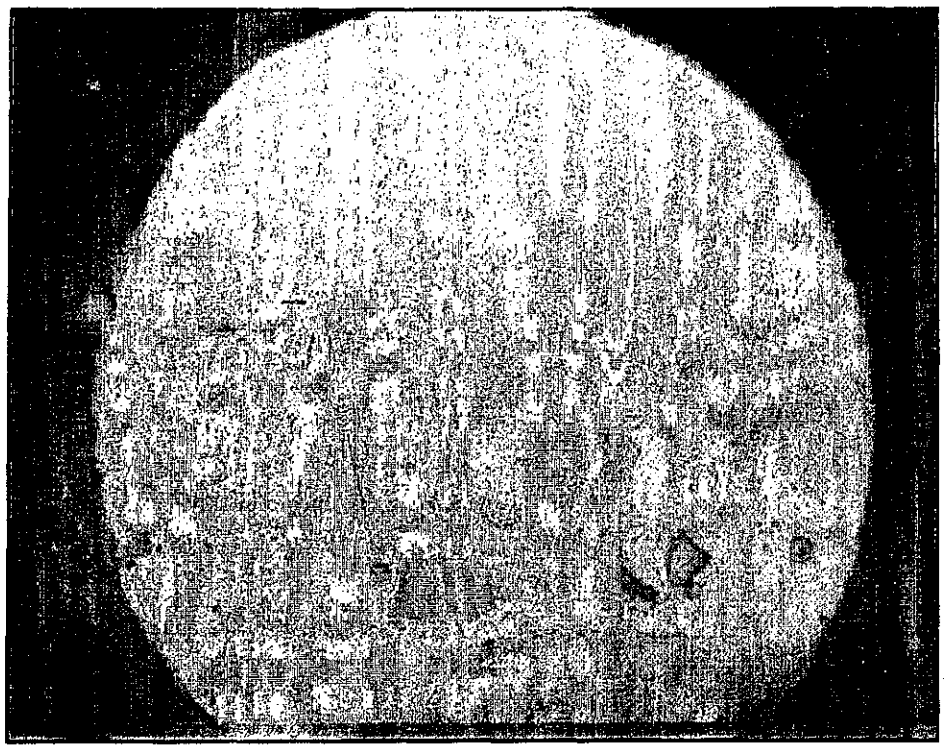


FIG. 8

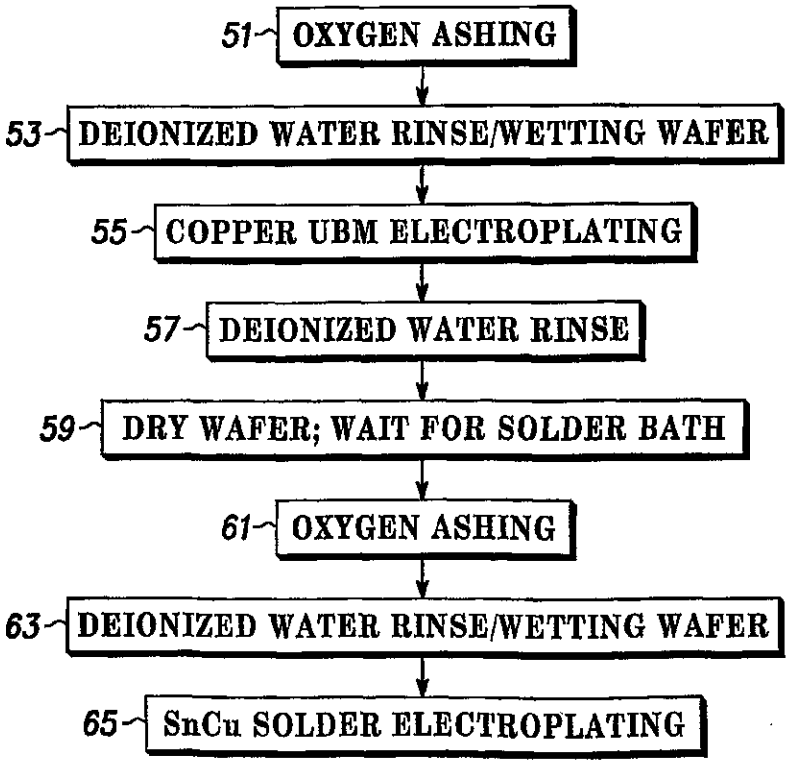


FIG. 9 - PRIOR ART -

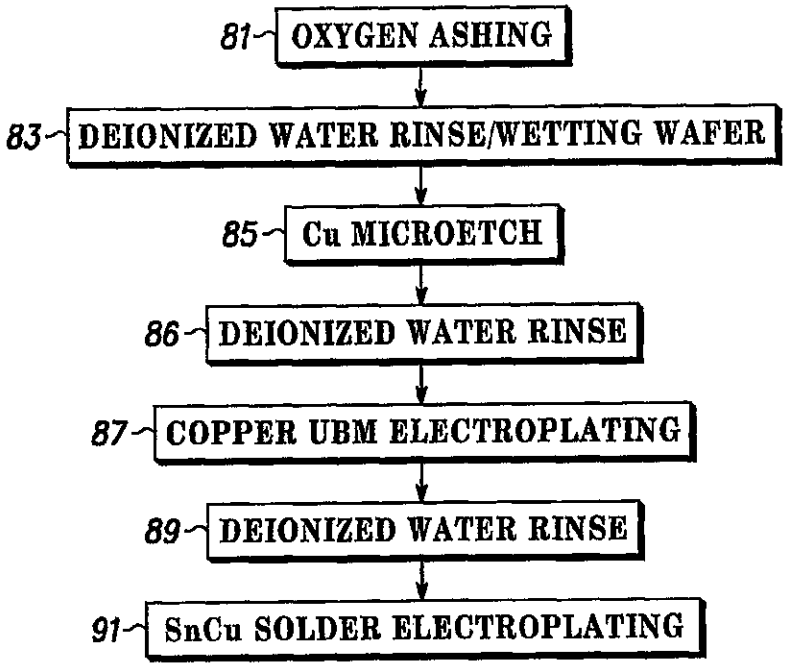


FIG. 10

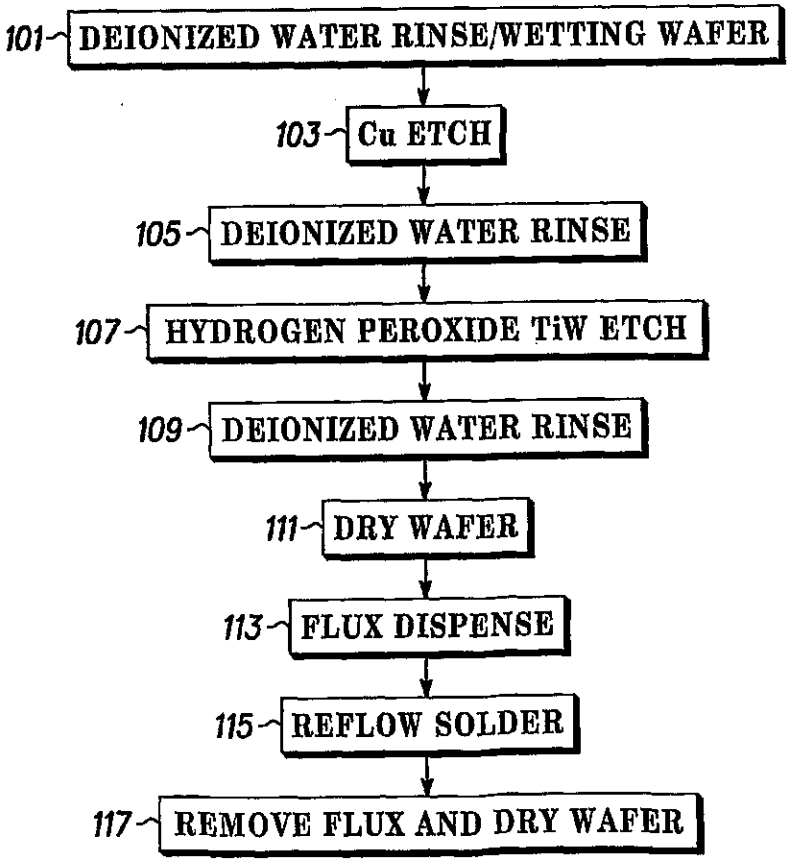


FIG. 11 - PRIOR ART -

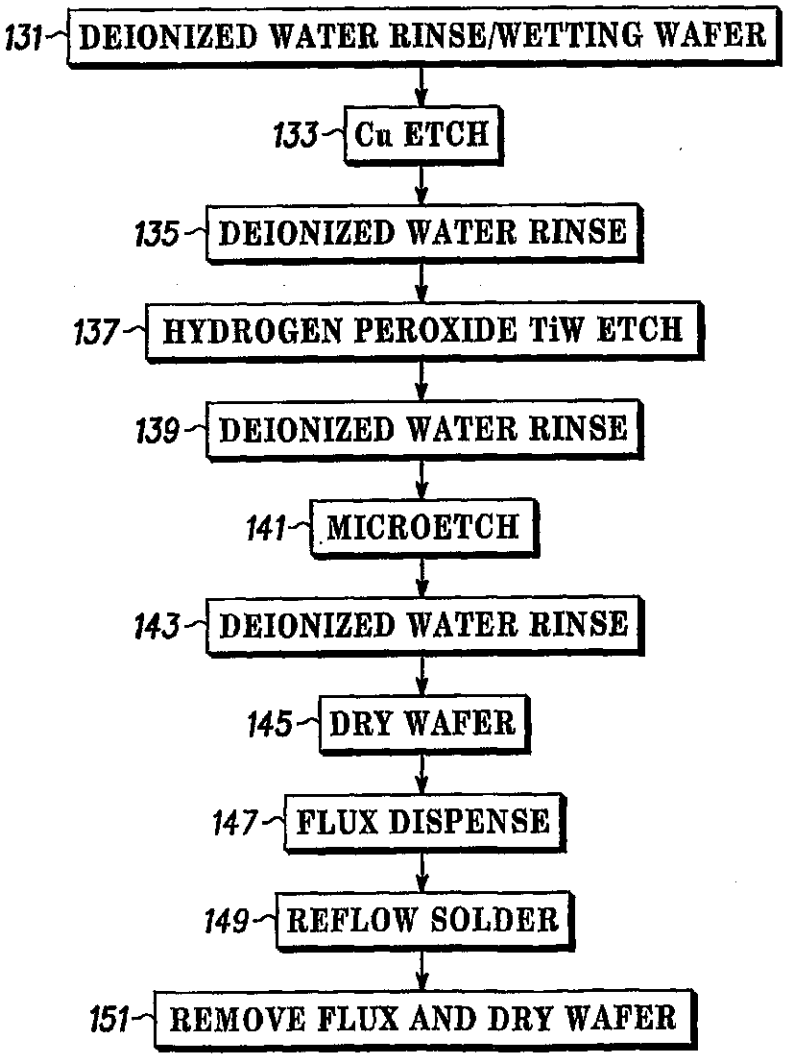

131
DEIONIZED WATER RINSE/WETTING WAFER
133
Cu ETCH
135
DEIONIZED WATER RINSE
137
HYDROGEN PEROXIDE TiW ETCH
139
DEIONIZED WATER RINSE
141
MICROETCH
143
DEIONIZED WATER RINSE
145
DRY WAFER
147
FLUX DISPENSE
149
REFLOW SOLDER
151
REMOVE FLUX AND DRY WAFER

FIG. 12

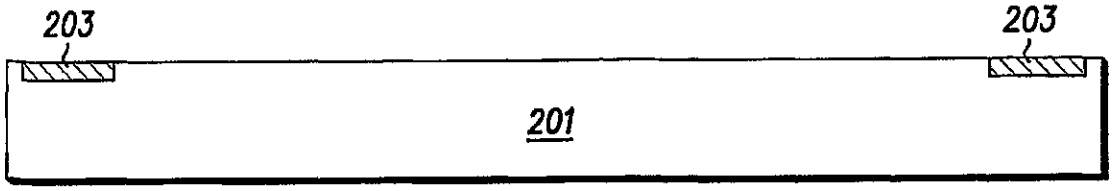


FIG. 13

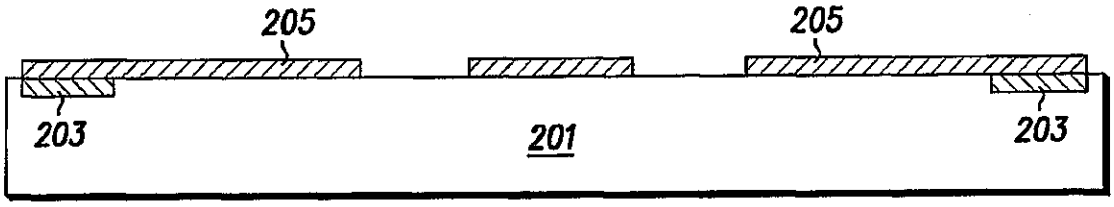


FIG. 14

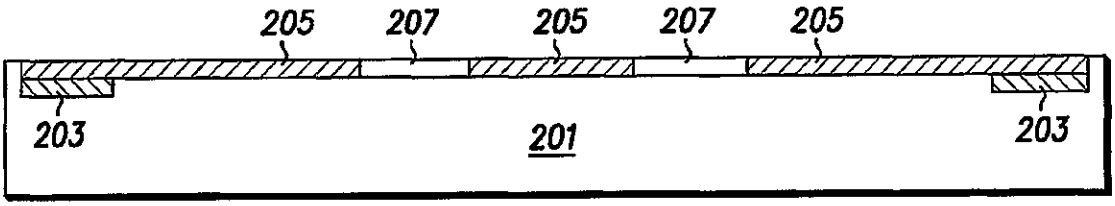


FIG. 15

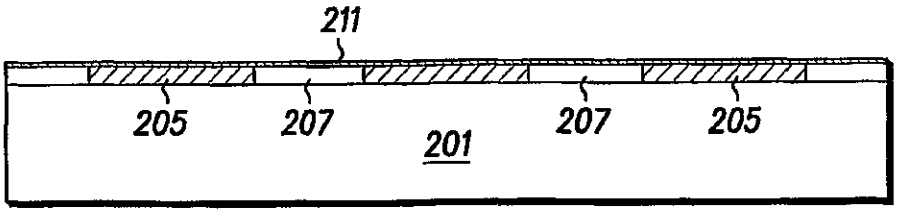


FIG. 16

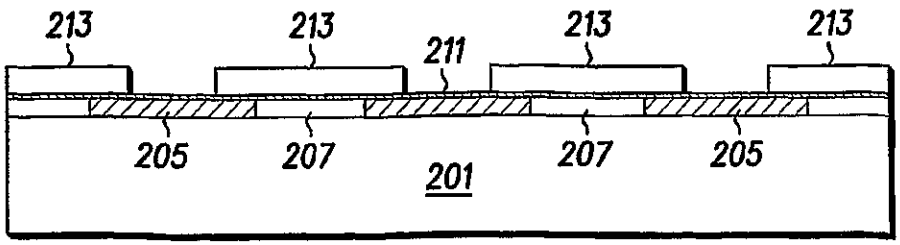


FIG. 17

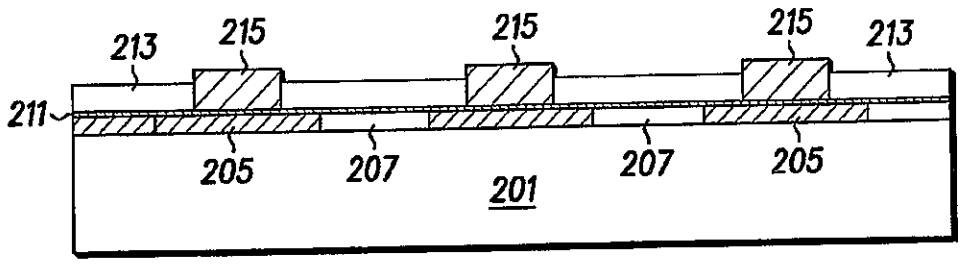


FIG. 18

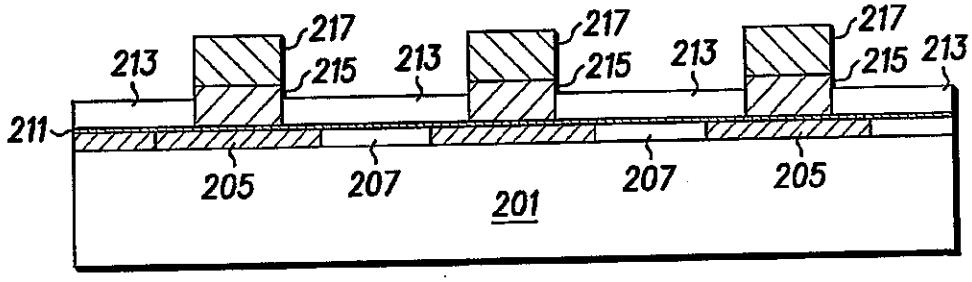


FIG. 19

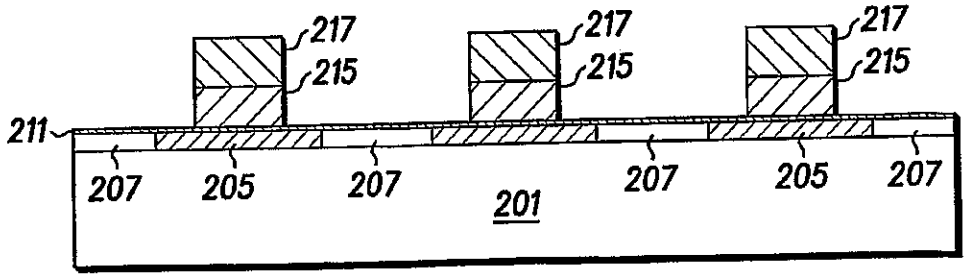


FIG. 20

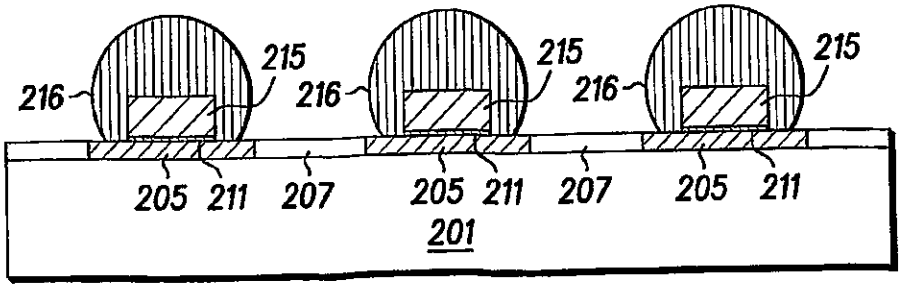


FIG. 21